

CALL FOR PAPER



**16th European Advanced Technology Workshop
ON MICROPACKAGING AND THERMAL
MANAGEMENT
POITIERS FUTUROSCOPE
8 & 9 MARCH 2023**



Conference Chair: Jean-Yves SOULIER (Safran Data Systems)

Technical Program Committee:

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Sandrine FENEYROU (Safran Data Systems)

Jean-Pierre FRADIN (ICAM)

We are pleased to open the call for papers of the 16th Advanced Technology Workshop on Micropackaging and Thermal Management which will be held in **Poitiers Futuroscope in 8th and 9th March 2023**. This yearly conference has grown year after year by the number of presented papers and attendees. This 16th edition will be the opportunity to resume technical exchanges after 3 years of Covid-19 pandemic.

Be part of a successful 2023 edition and be sure to submit your abstract on time. The workshop sessions will include the following topics. Papers are invited in following areas:

- **Cooling solutions for microelectronics packaging,**
- **Micro-cooling solutions,**
- **Heat conductive materials at chip, board, sub-system and system levels,**
- **Advances in PCBs for thermal management,**
- **Thermal modeling and simulation,**
- **Heatsinks, heat pipes and other cooling products,**
- **Liquid and phase change cooling,**
- **New cooling solutions,**
- **Overviews or examples of products, systems cooling, power electronics, automotive transport,**
- **Thermal management of optoelectronics components (LEDs, IR sensors...),**
- **Reliability of electronic components over extended temperature range or submitted to temperature variation,**
- **Thermal management aspects of 3D integration: thermal interface materials, dissipation from PCB embedded components.**

Speakers will submit 200-300 words abstract detailing their presentation (20 minutes + 5 minutes for questions), no later than **2nd November 2022**.

Speakers pay a reduced registration fee (including MERCURE hotel accommodation for 2 nights and meals) and are also requested to attend the entire workshop to maximize opportunities of exchanging with other attendees and exhibitors.

Notification of acceptance by the Technical Committee: **25 November 2022**.

After notification of acceptance, you commit to attend the workshop or delegate someone else.

Please respond to IMAPS by e-mail: **imaps.france@orange.fr**

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